

IN THE CLAIMS

The following includes the entire set of pending claims including mark-ups.

Please amend Claims 1-9.

Please add Claims 10-20.

1. (currently amended) An electroconductive contact probe holder for supporting a plurality of contact units for contacting an object, comprising:

a base plate member made of a first material and provided with an opening therein therethrough; and

a holder hole forming member made of a second material and filled in said opening substantially without extending outside said opening;

a plurality of holder holes being passed across a thickness of said holder hole forming member each for receiving a contact unit therein.

2. (currently amended) [[An]] The electroconductive contact probe holder according to claim 1, wherein said first material comprises a member selected from a group consisting of metallic material, semiconductor material, ceramic material and glass material.

3. (currently amended) [[An]] The electroconductive contact probe holder according to claim 1, wherein said second material comprises a plastic material.

4. (currently amended) [[An]] The electroconductive contact probe holder according to claim 1, wherein a film is formed over an inner circumferential surface of said opening.

5. (currently amended) [[An]] The electroconductive contact probe holder according to claim [[1]] 4, wherein said film is made of a material that promotes bonding between said holder hole forming member and said base plate.

6. (currently amended) [[An]] The electroconductive contact probe holder according to claim [[1]] 4, wherein said film is made of a material that promotes electric insulation between said holder hole forming member and said base plate.

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7. (currently amended) [[An]] The electroconductive contact probe holder according to claim [[1]] 4, wherein an engagement feature is formed on [[an]] the inner circumferential surface of said opening.

8. (currently amended) [[An]] The electroconductive contact probe holder according to claim 7, wherein said base plate member is made of a silicon wafer and said engagement feature comprises an inwardly directed ridge formed by anisotropically etching said inner circumferential surface of said opening.

9. (currently amended) [[An]] The electroconductive contact probe holder according to claim 1, wherein a stress relieving opening is formed adjacent said opening having said holder hole forming portion filled therein.

10. (new) An electroconductive contact probe holder for supporting a plurality of contact units for contacting an object, comprising:

a base plate member made of a first material and provided with an opening therethrough, wherein a film is formed over an inner circumferential surface of said opening; and

a holder hole forming member made of a second material and filled in said opening substantially without extending outside said opening;

a plurality of holder holes being passed across a thickness of said holder hole forming member each for receiving a contact unit therein.

11. (new) The electroconductive contact probe holder according to claim 10, wherein said first material comprises a member selected from a group consisting of metallic material, semiconductor material, ceramic material and glass material.

12. (new) The electroconductive contact probe holder according to claim 10, wherein said second material comprises a plastic material.

13. (new) The electroconductive contact probe holder according to claim 10, wherein said film is made of a material that promotes bonding between said holder hole forming member and said base plate.

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14. (new) The electroconductive contact probe holder according to claim 10, wherein said film is made of material that promotes electric insulation between said holder hole forming member and said base plate.

15. (new) The electroconductive contact probe holder according to claim 10, wherein an engagement feature is formed on the inner circumferential surface of said opening.

16. (new) The electroconductive contact probe holder according to claim 15, wherein said base plate member is made of a silicon wafer and said engagement feature comprises an inwardly directed ridge formed by anisotropically etching said inner circumferential surface of said opening.

17. (new) The electroconductive contact probe holder according to claim 10, wherein a stress relieving opening is formed adjacent said opening having said holder hole forming portion filled therein.

18. (new) An electroconductive contact probe holder for supporting a plurality of contact units for contacting an object, comprising:

a base plate member made of a first material and provided with an opening therethrough, wherein said first material comprises a member selected from a group consisting of metallic material, semiconductor material, ceramic material, and glass material; and

a holder hole forming member made of a second material and filled in said opening substantially without extending outside said opening;

a plurality of holder holes being passed across a thickness of said holder hole forming member each for receiving a contact unit therein.

19. (new) The electroconductive contact probe holder according to claim 18, wherein a film is formed over an inner circumferential surface of said opening, said film being made of a material that promotes bonding between said holder hole forming member and said base plate.

20. (new) The electroconductive contact probe holder according to claim 18, wherein a film is formed over an inner circumferential surface of said opening, said film being made of a material that promotes electric insulation between said holder hole forming member and said base plate.

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